The Strongest Editorial Team Provides Professional Contents for China Semiconductor Manufacturing Industry
The Most Powerful and Effective Database Sourced from SEMICON China
Highest Value at Affordable and Attractive Price
Advanced CTP Printing Technology Ensures Your Original Ad. Design and Color

SEMICONDUCTOR Manufacturing
半导体制造

2009
Tailored Content for China's Technical Professionals

*Semiconductor Manufacturing* magazine provides technology and market information for managers and engineers in semiconductor industry. By leveraging the strength of SEMI – the global industry association, *Semiconductor Manufacturing* offers overviews of current technology trends and challenges with the best papers presented at SEMI's technical conferences.

The circulation of *Semiconductor Manufacturing* magazine has reached over 10,000. SEMICON China March special issue circulation is 20,000.

*Semiconductor Manufacturing* magazine is published by SEMI.
China's semiconductor manufacturing is catching up the world advanced technology train by getting 65nm logic volume production by the end of 2008. R&D of 45nm and 32nm process is going on smoothly. In the next three years, the bulk of new capacity to be added in China will be for 300 mm and 200 mm wafers fabs. Large diameter fabs will account for more than 83% of China's total wafer capacity by 2010 and the 300 mm capacity is almost identical to the 200 mm capacity at the same time frame.

Since 2001, the materials industry has had consecutive years of growth and will reach a forecasted size of $46 billion in 2008. Looking at materials on a regional basis, China is experiencing the highest growth rate at 25 percent year-on-year.

Fab material vendors reported strong sales growth in China in 2006 as result of the availability of China's newly-added 200mm -300mm wafer process capacity. As more 300mm wafer process capacity will be installed in China from 2007 to 2010, fab material growth from 2006 to 2010 will be even stronger and the CAGR may reach 30.6% in that period.
The Strongest Editorial Team Provides Professional Content

With a team of six senior editors, Semiconductor Manufacturing magazine goes beyond the efforts of most technical magazines to bring readers authoritative relevant content.

April Peng
Editor-in-Chief
MS, Material Science, Wuhan University of Technology

- 8 years experience in industry media and 4 years as editor-in-chief at Semiconductor Manufacturing
- More than 50 interviews, comments and technical articles published in Semiconductor Manufacturing
- 3 years experience as a process engineer at Institute of Semiconductor, Chinese Academy of Science

Tel: 86.10.51906086 Email: apeng@semi.org

Hongtao Sun
Contributing Editor
MS, Tsinghua University and Researcher in Cambridge University

- Former CTO of 48 Research Institute with more than 30 years experience in semiconductor industry
- In charge of technical article translation and editing for Semiconductor Manufacturing

Email: hsun@semi.org

Doris Dong
Executive Reporter
BE, Electronics Engineering, Beijing University of Technology

- Conducted more than 80 interviews with industry CEOs and executives with articles and comments published at magazine and website
- 8 years marketing experience as PR supervisor at Kodak China
- 4 years in SGNEC as marketing and sales representative
- In charge of industry executive interview column and market related content for Semiconductor Manufacturing

Tel: 86.21.50270909-239 Email: ddong@semi.org

Lily Feng
Contributing Editor
MS, Communications and Signal Processing, University of Newcastle upon Tyne, UK

- Market Research Manager of SEMI China, 3 industry research reports released - “China Equipment Subsystems, Components, and Parts Vendors Overview”, “China Semiconductor Wafer Fab and Foundry Outlook” and “China Domestic Fab Equipment Suppliers”
- 5 years industry research experience in SEMI and edaily
- More than 10 articles published in Semiconductor Manufacturing

Tel: 86.21.50270909-238 Email: lifeng@semi.org

Flora Qin
Technical Editor
MS, Microelectronics Materials, Katholieke Universities Leuven, Belgium

- Conducted more than 30 interviews with industry technical leaders
- 3 years experience as R&D engineer at Hua Hong NEC
- In charge of magazine technical story and technical article editing for Semiconductor Manufacturing

Tel: 86.21.50270909-275 Email: wqin@semi.org

Bin Zhou
Contributing Editor
MS, Materials with Business, Queen Mary, University of London, UK

- Market Analyst of SEMI China, specialized in packaging & testing industry
- 3 years experience as R&D engineer at ASE
- In charge of packaging & test technical articles and industry interview for Semiconductor Manufacturing

Tel: 86.21.50270909-279 Email: bzhou@semi.org

With a team of six senior editors, Semiconductor Manufacturing magazine goes beyond the efforts of most technical magazines to bring readers authoritative relevant content.
The editorial direction of *Semiconductor Manufacturing* magazine is guided by SEMI China Technical Committees—the volunteers of the most elite group of technical leaders.

*Semiconductor Manufacturing* magazine shares the same technical committee with ISTC/CSTIC, One of China largest technical conferences merged by ISTC (International Semiconductor Technology Conference) and CSTIC (China Semiconductor Technology International Conference).
## Semiconductor Manufacturing - Editorial Calendar 2009

### Important Deadlines

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<th>JAN/FEB</th>
<th>MARCH</th>
<th>APRIL</th>
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### Issue Focus

#### Lithography

- **Cover Story**
  - **Immersion Lithography**
  - **Technology**
    - **Double Patterning**
    - **Advanced Photoresist**
    - **Deep Etch**
    - **2009 Industry Forecast**

#### Transistors

- **Cover Story**
  - **Advanced Memory Devices**
  - **High-κ/Metal Gate Technology**
  - **3D Packaging**
  - **SEMICON China Product Preview**

#### Yield

- **Cover Story**
  - **Process Control in the Sub-micron CMOS Era**
  - **DFM for Yield Enhancement**
  - **EHS**
  - **SEMICON China Report**

#### Interconnect

- **Cover Story**
  - **CMP Process & Consumables**
  - **Porous Low-κ Dielectrics and Airgap Technology**
  - **DFM & Cu Interconnect**
  - **Cu Electroplating for Through-Silicon-Via**

#### ATE

- **Design for Test (DFT)**
- **Test for Yield Learning**
- **Electroless Process on Wafer**
- **Etching**
- **Overall Equipment Efficiency**

### Special Coverage

- **Photovoltaic**
- **FPD**
- **MEMS**
- **Organic Semiconductor**
- **Photovoltaic**

### Bonus Distribution

- **SEMICON Korea**
- **SOLARCON Korea**
- **SEMICON China**
- **SOLARCON China**
- **FPD China**
- **ISTC/CSTIC**
- **SEMICON Singapore**
- **SOLARCON Singapore**
- **ASMC**
- **FPD Taiwan**
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<th>Deposition</th>
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<td>Advances in EUV Lithography</td>
<td>3D Packaging</td>
<td>CVD/PVD Extensibility</td>
<td>Inspection Technology Innovation</td>
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<td>Manufacturing Integration</td>
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<td>TSV</td>
<td>ALD Process and Precursor Materials</td>
<td>Standalone and Integrated Metrology</td>
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<td>ATE</td>
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<td>Device Reliability</td>
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<td>Strained Silicon</td>
<td>Wire Bonding</td>
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<td>Wafer Level Packaging</td>
<td>SOI</td>
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<td>III-V</td>
<td>Nanotech</td>
<td>Photovoltaic</td>
<td>MEMS</td>
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SEMICON West PV Japan SEMICON Taiwan IC China SEMICON Europa BMIS ISS Greater China SEMICON Japan
Special Columns for China Readers

Based on our readers’ feedback, we design special columns to readers in China. In addition to cutting-edge technology overviews and solutions articles, we have Semiconductor ABC column to new engineers and managers with basic process know-how. Photovoltaic, FPD, MEMS and III-V semiconductors remains in our scope of coverage. Development trends and data from both the global and mainland China semiconductor manufacturing industry will be introduced in the Market Watch and News & Views columns.
Semiconductor Manufacturing March issue will be a special issue for SEMICON China 2009. This special issue will highlight the show and programs during SEMICON China. Show products and technology, expert opinions about technology development and floor plan will be introduced in this special issue.

20,000 copies of special issue will be distributed to magazine subscribers, pre-registered visitors before the show, and to professional visitors at the registration desk during the show.

On site, we also have 15,000 copies of the Daily News during SEMICON China show. They will be individually handed to each attendee as they enter the show. Content of Daily News will be exhibitors and visitor interview, event reports, show product introduction, China & global semiconductor market data, and etc. 6,000 copies of Daily News will be distributed on March 17, while 5,000 on March 18 and 4,000 on March 19.

SEMICON China 2008 Visitors’ Main Job Function

- 24% Wafer Fabrication and Process Engineering
- 15% Marketing and Sales
- 12% Manufacturing/Engineering/Operations Management
- 11% Research & Development Engineering
- 10% Purchasing/Procurement
- 9% Assembly/Packaging Engineering
- 8% Quality Assurance and Test Engineering
- 3% Other
- 3% Executive Management
- 2% Facilities Engineering/Engineering Support
- 1% Training
- 1% Environment, Health and Safety
- 1% Financial/Industry Analyst
- 1% Government/Public Policy

66% of Visitors Represent Engineering Job Functions.

SEMICON China 2008 Total Verified Visitors: 39314
Reading Habit Survey

Challenge at work

Process Stabilization
Engineer, BCD Semiconductor

Technical Challenge
Manager, Founder Microelectronics

Trend of Microelectronics Manufacturing Technology
Engineer, Rohm & Haas

Cleanroom Management
Director, HHNEC

Test Disturbing
Engineer, Panasonic Semiconductor

Reliability Analysis of Packaging
Engineer, BCD Semiconductor

How to Change from Au to Cu Bonding
Engineer, GEM Electronics

Favorite Articles in Semiconductor Manufacturing Voted by Readers:

Optimizing Yield and Wafer Fab Productivity through Yield Sensitive Dispatch
Contributed by National Semiconductor

RF System in Package
Contributed by STATSChipPAC

Printing Electronics Technology
Contributed by Motorola

CIM: The Central Nerves of Advanced Factory Management System
Written by Lily Feng, Contributing Editor

What Kind of R&D is Required in China
Written by Flora Qin, Technical Editor

From Semiconductor to PV
Written by James Mo, Contributing Editor

The average time to read one issue of Semiconductor Manufacturing magazine:

- 51% more than 1 hour
- 38% 30min-1 hour
- 11% less than 30min
Fresh Database
10000 + 20000

As the official publication of SEMICON China, visitors to the show are guaranteed to be your target audiences. Attracting more than 30,000 visitors to SEMICON China every year, Semiconductor Manufacturing magazine makes use of this annual industry gathering to update its reader database - giving it an exclusive access to the most comprehensive, timely list in China.

Magazine Circulation
Number is 10,000
(As of Oct. 15, 2008)

SEMICON China 2009
March Special Issue
Number is 20,000

Please contact customer service staff for database service including:
- Direct Mailing Service
- PR and Technical Seminar Assistance
- Investigation and Research
- Email Delivery Service

SMIC(Shanghai, Beijing, Tianjin, Chengd) 1235
HHNEC 478
GSMC 462
Hyntix-ST 327
TSMC 208
ASMC 171
Hejian 156
CSCM 137
BCD 110
Belling 68

ASE 207
Numonyx 185
STATS ChipPAC 176
Amkor(Shanghai) 133
Samsung(Suzhou) 101
JCET 93
Renesas 80
Fairchild(Suzhou) 75
Nantong-Fujitsu 74

*As of Sep. 2008
**Advertising Deadlines**

**Space Deadline:** 10th of each month prior to issue date.

**Materials Deadline:** 15th of each month prior to issue date. (confirm with Production Department)

**Printing Process:** Computer-to-plate, heat-set web offset, perfect-bound.

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**Mechanical Specifications**

**Publication Trim Size:** 200mm x 267mm (7-7/8” x 10-1/2”)

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<td>8x1-1/4</td>
<td>12x8-3/4</td>
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<td>7x8-3/4</td>
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**Crop Marks:** Place crop marks 6mm(1/4") outside of trim.

**Safety Margin:** Keep all live matter 10mm(3/8") from trim edges.

**Gutter Safety:** Between body copy-allow 6mm(1/4") on each side of the gutter, 12mm(1/2") total.

Between headline letters-allow 3mm(1/8") on each side of the gutter, 6mm(1/4") total.

Between headline words-allow 5mm(3/16") on each side of the gutter, 10mm(3/8") total.

**Line Screen:** 133 lpi

**Maximum Density:** 4/C–280% ; 2/C–160% ; B&W–80%

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**Materials Requirements**

**Digital Materials are Required. SWOP Standards Apply.**

Supply all ad materials with crop, registration and center marks, offset 1/4" (6 mm) from trim.

Provide ad files on Mac-compatible CDs or DVDs with hard copy proofs and a copy of the insertion order per the specifications below.

**Required File Format:** PDF ver. 1.3. Must be created strictly to our specifications using Acrobat Distiller ver. 4.0 or later. Prepare files per materials requirements prior to PDF conversion.

**Alternate File Formats:** PDF format is preferred. EPS and TIFF files are acceptable. Provide all fonts and graphics with page document file. Embed all fonts and graphics at 300 dpi (118 ppc).

**Color:** CMYK, only, plus a fifth PMS color when purchased. RGB, Index and Lab colors are not accepted.

**Graphics:** Prepare images at a resolution of 300 dpi (118 ppc) and line work at 2400 dpi (945 ppc). Convert all color to CMYK. Import all images at 100% with no rotation in EPS or Tiff format. Do not use JPEG or LZW compression or embed color profiles. Do not nest EPS file into other EPS files. Outline fonts and provide files of all embedded images.

**Proofs:** Digital, press or off-press proofs which meet SWOP specifications are required for all color ads. For B/W ads, a laser copy printout must be provided. Supply all proofs at 100% of ad size with color control patches applied.

**Media Labeling:** Include agency name, contact and phone number, advertiser name, ad name/number, publication and issue date.

**Alterations:** Alterations to ad materials will incur additional charges. Proofs of alterations are not provided. New files must be supplied for non-editable materials, extensive alterations and 4-color changes. Semiconductor Manufacturing Magazine China cannot provide translations to the ad materials.
Rate Card

The price is the same for 4C, 2C, BW ads.

$1000 will be added to earned rate if using 5th color while $2000 for metallic ink.

Please contact your customer service representatives for cover/special position availability.

10% to display rate will be added to special positions.

This rate is for SEMI member only. Non-member rate add 50%.

SEMIICON China 2009 Daily News

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Sales Representatives

CHINA
Ellen Xie
Tel: 86.21.50270909
Fax: 86.21.50274830
Email: exie@semi.org

UNITED STATES
Barbara Weitzel
Tel: 1.408.943.7065
Fax: 1.408.943.7066
Email: bweitzel@semi.org

* Please allow 3mm bleeds.
www.semi.org.cn

www.semi.org.cn, launched by SEMI China, is NOT about SEMI, BUT aims to serve as a platform for the semiconductor industry. Redesigned website will provide the global latest and in-depth semiconductor industry news, articles videos and PPT.
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* GIF or JPEG format are acceptable. GIF或JPEG文件均可。

**Sales Representatives**

**CHINA**

Ellen Xie  
Tel: 86.21.50270909  
Fax: 86.21.50274830  
Email: exie@semi.org

**UNITED STATES**

Barbara Weitzel  
Tel: 1.408.943.7065  
Fax: 1.408.943.7066  
Email: bweitzel@semi.org
Shanghai
Add: Rm.201, 295 Zuchongzhi Road, Zhangjiang Hi-tech Park, Pudong, Shanghai, 201203, China
Tel: 86.21.50270909
Fax: 86.21.50274830
Email: mding@semi.org

Beijing
Add: 18G, Tower 2, Hua Ao Ctr. 31 Zizhuyuan Rd. Haidian Dist. Beijing, 100089, China
Tel: 86.10.51906086
Fax: 86.10.51906087

SALES REPRESENTATIVES
UNITED STATES
Barbara Weitzel
Tel: 1.408.943.7065
Fax: 1.408.943.7066
Email: bweitzel@semi.org

CHINA
邓佩蓉
Polly Teng
Tel: 86-21-50270909
Fax: 86-21-50274830
Email: pteng@semi.org

Ellen Xie
Tel: 86-21-50270909
Fax: 86-21-50274830
Email: exie@semi.org

Christine Dong
Tel: 86-21-50270909
Fax: 86-21-50274830
Email: cdong@semi.org

Lucia Le
Tel: 86-21-50270909
Fax: 86-21-50274830
Email: lle@semi.org

Laura Wang
Tel: 86-21-50270909
Fax: 86-21-50274830
Email: lwang@semi.org